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TOOLS AND METHODS FOR DISUNITING SEMICONDUCTOR WAFERS

ABSTRACT

5 A tool for disuniting two wafers, at least one of
which is for use in fabricating substrates for
microelectronics, optoelectronics, or optics, the tool
comprising two gripper members suitable for being fixed
temporarily to respective opposite faces of the two
10 wafers that are united with each other, and a disuniting
control device suitable for moving said members relative
to each other. The tool is remarkable in that the
disuniting control device comprises an actuator for
positively displacing said gripper members and for
15 inducing controlled flexing in at least one of said
members. This makes it easier to disunit the wafers
while reducing the risk of damaging them. The invention
is applicable to disuniting wafers that have been
weakened by implantation, that have been temporarily
20 bonded together, etc.